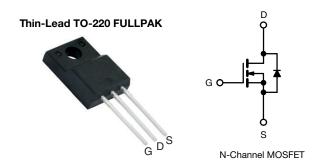
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COMPLIANT

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# **E Series Power MOSFET with Fast Body Diode**



PRODUCT SUMMA	RY	
V <sub>DS</sub> (V) at T <sub>J</sub> max.	700	)
R <sub>DS(on)</sub> max. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	0.18
Q <sub>g</sub> max. (nC)	106	3
Q <sub>gs</sub> (nC)	14	
Q <sub>gd</sub> (nC)	33	
Configuration	Sing	le

#### **FEATURES**

- Fast body diode MOSFET using E series technology
- Reduced t<sub>rr</sub>, Q<sub>rr</sub>, and I<sub>RRM</sub>
- Low figure-of-merit (FOM) Ron x Qg
- Low input capacitance (Ciss)
- Low switching losses due to reduced Q<sub>rr</sub>
- Ultra low gate charge (Qg)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

#### **APPLICATIONS**

- Telecommunications
  - Server and telecom power supplies
  - Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Consumer and computing
  - ATX power supplies
- Industrial
  - Welding
  - Battery chargers
- Renewable energy
   Solar (PV inverters)
- Switch mode power supplies (SMPS)
- Applications using the following topologies
  - LCC
  - Phase shifted bridge (ZVS)
  - 3-level inverter
  - AC/DC bridge

ORDERING INFORMATION	
Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free	SiHA21N65EF-E3
Lead (Pb)-free and halogen-free	SiHA21N65EF-GE3

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub>	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			$V_{DS}$	650	V	
Gate-source voltage			$V_{GS}$	± 30		
Continuous dusin suggest /T 150 °C\ 6	\/ -+ 10\/	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I <sub>D</sub>	21		
Continuous drain current (T <sub>J</sub> = 150 °C) <sup>e</sup>	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		13	Α	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	53		
Linear derating factor				0.28	W/°C	
Single pulse avalanche energy b			E <sub>AS</sub>	367	mJ	
Maximum power dissipation			P <sub>D</sub>	35	W	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope	T <sub>J</sub> = 125 °C		-11//-14	37	)//	
Reverse diode dV/dt <sup>d</sup>			dV/dt	31	- V/ns	
Soldering recommendations (peak temperature) c	for	or 10 s 300 °C				
Mounting torque	M3 s	screw		0.6	Nm	

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 5.1 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ ,  $dI/dt = 100 \text{ A/}\mu\text{s}$ , starting  $T_J = 25 \,^{\circ}\text{C}$
- e. Limited by maximum junction temperature



Vishay Siliconix

THERMAL RESISTANCE RATI	NGS			
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R <sub>thJA</sub>	-	65	°C/W
Maximum junction-to-case (drain)	$R_{thJC}$	-	3.6	C/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		650	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	=.	0.67	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	-	4	V
Onto anima lankana		V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-source leakage	I <sub>GSS</sub>		V <sub>GS</sub> = ± 30 V	-	-	± 1	μΑ
Zana anto coltano durio accurant		V <sub>DS</sub> =	= 520 V, V <sub>GS</sub> = 0 V	-	-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 520 \	/, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	500	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 11 A	-	0.15	0.18	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 30 V, I <sub>D</sub> = 11 A	-	7.0	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>		$V_{GS} = 0 V$ ,	-	2322	-	
Output capacitance	C <sub>oss</sub>		$V_{DS} = 100 \text{ V},$	-	105	-	=
Reverse transfer capacitance	C <sub>rss</sub>	f = 1 MHz		-	4	-	pF
Effective output capacitance, energy related <sup>a</sup>	$C_{o(er)}$			-	84	-	
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>	V <sub>DS</sub> = 0 \	$V_{DS} = 0 \text{ V to } 520 \text{ V}, V_{GS} = 0 \text{ V}$		293	-	
Total gate charge	Qg			-	71	106	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$I_D = 11 A, V_{DS} = 520 V$	-	14	-	nC
Gate-drain charge	Q <sub>gd</sub>	7		-	33	-	
Turn-on delay time	t <sub>d(on)</sub>			=.	22	44	
Rise time	t <sub>r</sub>	$V_{DD} = 520 \text{ V}, I_D = 11 \text{ A},$		=	34	68	
Turn-off delay time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		68	102	ns ns
Fall time	t <sub>f</sub>				42	84	
Gate input resistance	$R_g$	f = 1 MHz, open drain		=	0.78	-	Ω
Drain-Source Body Diode Characteristic	s						•
Continuous source-drain diode current	I <sub>S</sub>	MOSFET sym showing the	MOSFET symbol showing the		-	21	
Pulsed diode forward current	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	53	A
Diode forward voltage	V <sub>SD</sub>	T <sub>,J</sub> = 25 °C	C, I <sub>S</sub> = 11 A, V <sub>GS</sub> = 0 V	-	0.9	1.2	V
Reverse recovery time	t <sub>rr</sub>			-	160	-	ns
Reverse recovery charge	Q <sub>rr</sub>		$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 11 \text{A},$		1.2	-	μC
Reverse recovery current	I <sub>RRM</sub>	dl/dt = 100 A/μs, V <sub>R</sub> = 25 V		_	14	-	A

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$
- b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

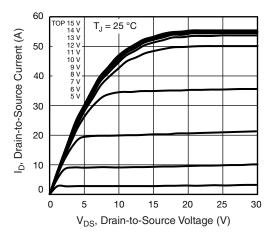


Fig. 1 - Typical Output Characteristics

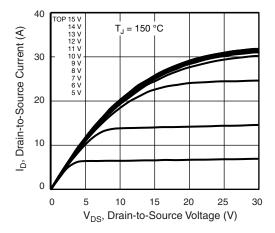


Fig. 2 - Typical Output Characteristics

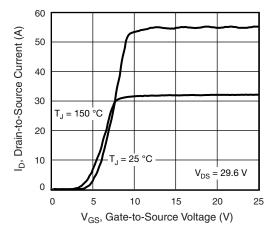


Fig. 3 - Typical Transfer Characteristics

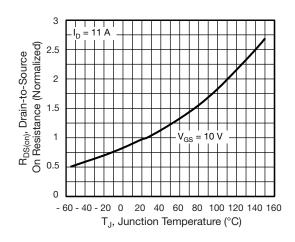


Fig. 4 - Normalized On-Resistance vs. Temperature

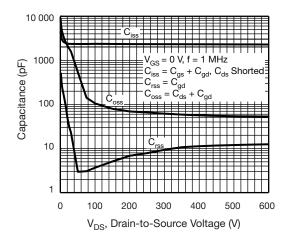


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

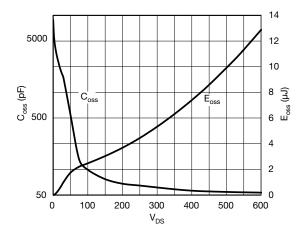


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 



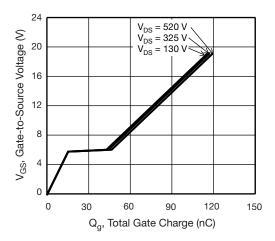


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

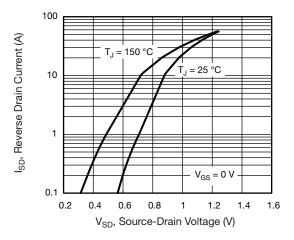


Fig. 8 - Typical Source-Drain Diode Forward Voltage

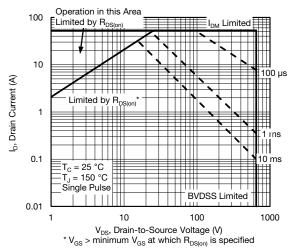


Fig. 9 - Maximum Safe Operating Area

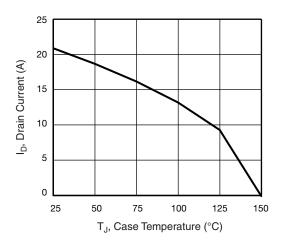


Fig. 10 - Maximum Drain Current vs. Case Temperature

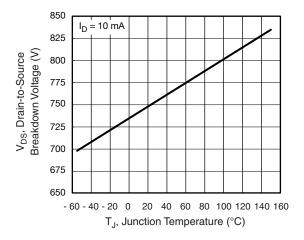


Fig. 11 - Temperature vs. Drain-to-Source Voltage



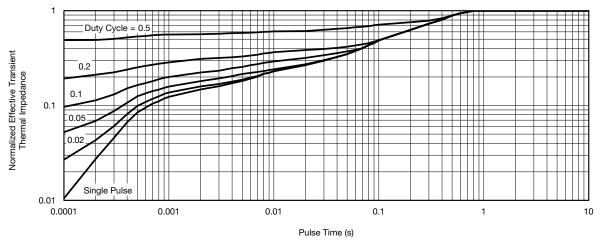


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

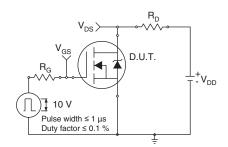


Fig. 13 - Switching Time Test Circuit

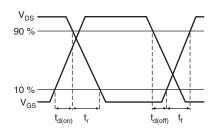


Fig. 14 - Switching Time Waveforms

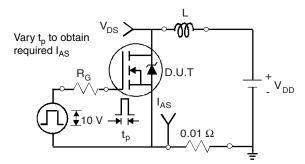


Fig. 15 - Unclamped Inductive Test Circuit

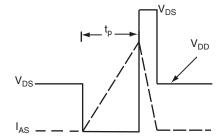


Fig. 16 - Unclamped Inductive Waveforms

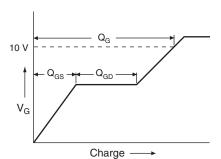


Fig. 17 - Basic Gate Charge Waveform

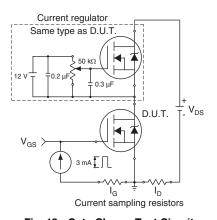
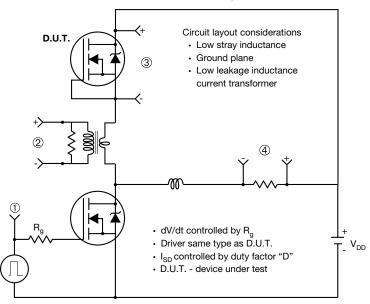


Fig. 18 - Gate Charge Test Circuit



#### Peak Diode Recovery dV/dt Test Circuit



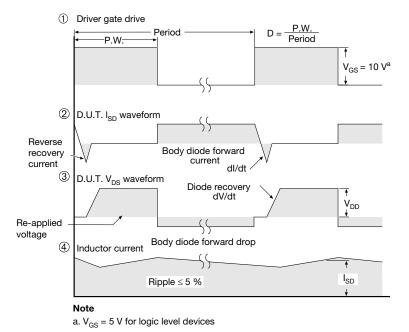


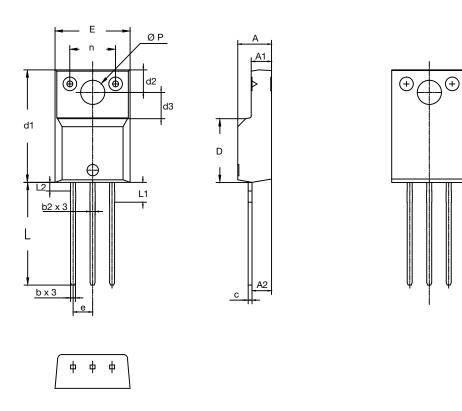
Fig. 19 - For N-Channel

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# **TO-220 FULLPAK Thin Lead**



SYMBOL	DIMENSIONS				
	MILLIN	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.30	4.70	0.169	0.185	
A1	2.50	2.90	0.098	0.114	
A2	2.50	2.70	0.098	0.106	
b	0.60	0.80	0.024	0.031	
b2	0.60	0.90	0.024	0.035	
С	=	0.60	-	0.024	
D	8.30	8.70	0.327	0.342	
d1	14.70	15.30	0.579	0.602	
d2	2.90	3.10	0.114	0.122	
d3	3.40	3.60	0.134	0.142	
E	9.70	10.30	0.382	0.406	
е	2.50	2.70	0.098	0.106	
L	13.40	13.80	0.528	0.543	
L1	2.50	2.80	0.098	0.110	
L2	-	1.20	-	0.047	
n	6.05	6.15	0.238	0.242	
ØΡ	3.00	3.40	0.118	0.134	

Revision: 12-Sep-16 1 Document Number: 62649



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